

Customer No.: 31561
Application No.: 10/709,179
Docket No.: 10544-US-PA

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Examiner: HA, NATHAN W.

Group Art Unit: 2814

In re PATENT APPLICATION of

Applicants : Chang et al.

Serial No. : 10/709,179

Filed : April 19, 2004

For : STACK-TYPE MULTI-CHIP
PACKAGE AND METHOD OF
FABRICATING BUMPS ON
THE BACKSIDE OF A CHIP

DO NOT ENTER.

N.H.

8/16/08

AMENDMENTS

) Attorney Docket: 10544-US-PA
) _____

The Commissioner is authorized to charge any fees required in connection with the filing of this paper to account No. 50-2620 (Order No.: 10544-US-PA)

AMENDMENTS AND RESPONSE TO OFFICE ACTION

United States Patent and Trademark Office
Customer Service Window
Mail Stop **AF**
Randolph Building
401 Dulany Street
Alexandria, VA 22314

Dear Sir:

The Office Action dated June 06, 2008, has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.